

### SEMITOP<sup>®</sup> 3

### 3-phase bridge inverter

#### SK 15 GD 126 ET

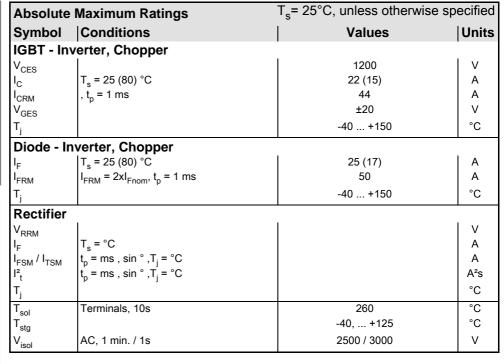
**Preliminary Data** 

#### Features

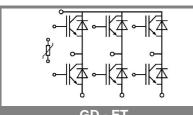
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded alumium oxide ceramic (DCB)
- Trench technology IGBT
- CAL High Density FWD
- Integrated NTC temperature sensor

### **Typical Applications**

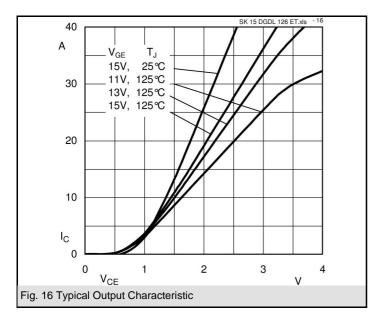
Inverter

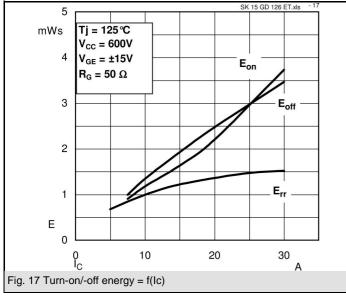


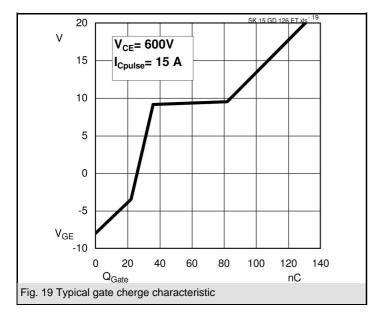
Characteristics		T <sub>s</sub> = 25°C	$T_s$ = 25°C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units	
IGBT - Inverter, Chopper						
$V_{CEsat} \\ V_{GE(th)} \\ V_{CE(TO)} \\ r_{T} \\ C_{ies} \\ C_{oes} \\ C_{res} \\ R_{th(j-s)} \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ \end{cases}$	$\begin{split}  I_{C} &= 15 \text{ A}, \ T_{j} = 25 \ (125) \ ^{\circ}\text{C} \\ V_{GE} &= V_{CE}, \ I_{C} &= 0,6 \text{ mA} \\ T_{j} &= 25 \ ^{\circ}\text{C} \ (125) \ ^{\circ}\text{C} \\ T_{j} &= 25 \ ^{\circ}\text{C} \ (125) \ ^{\circ}\text{C} \\ V_{CE} &= 25 \ V_{GE} &= 0 \ ^{\circ}\text{V}, \ f = 1 \ ^{\circ}\text{MHz} \\ V_{CE} &= 25 \ ^{\circ}\text{V}_{GE} &= 0 \ ^{\circ}\text{V}, \ f = 1 \ ^{\circ}\text{MHz} \\ V_{CE} &= 25 \ ^{\circ}\text{V}_{GE} &= 0 \ ^{\circ}\text{V}, \ f = 1 \ ^{\circ}\text{MHz} \\ v_{CE} &= 25 \ ^{\circ}\text{V}_{GE} &= 0 \ ^{\circ}\text{V}, \ f = 1 \ ^{\circ}\text{MHz} \\ v_{CE} &= 25 \ ^{\circ}\text{V}_{GE} &= 0 \ ^{\circ}\text{V}, \ f = 1 \ ^{\circ}\text{MHz} \\ v_{CE} &= 600 \ ^{\circ}\text{V}, \ ^{\circ}\text{V}_{GE} &= \pm 15 \ ^{\circ}\text{V} \\ I_{C} &= 15 \ ^{\circ}\text{A}, \ T_{j} &= 125 \ ^{\circ}\text{C} \\ \end{split}$	5	1,7 (2,2) 5,8 1 (0,9) 47 (73) 1,2 0,3 0,2 35 20 403 192	2,1 6,5 1,2 60 1,6	V V mΩ nF nF K/W ns ns ns ns	
t <sub>f</sub> E <sub>on</sub> E <sub>off</sub>	$R_{Gon} = R_{Goff} = 50 \Omega$ inductive load		1,63 1,93		ns mJ mJ	
Diode - In	verter, Chopper					
$\begin{array}{l} V_F = V_{EC} \\ V_{(TO)} \\ r_T \\ R_{th(j-s)} \\ I_{RRM} \\ Q_{rr} \\ E_{rr} \end{array}$	$ \begin{array}{l} I_{F} = 15 \text{ A}, \ T_{j} = 25 \ (125) \ ^{\circ}\text{C} \\ T_{j} = 25 \ ^{\circ}\text{C} \ (125) \ ^{\circ}\text{C} \\ T_{j} = 25 \ ^{\circ}\text{C} \ (125) \ ^{\circ}\text{C} \\ \hline \text{per diode} \\ \\ \text{under following conditions} \\ I_{F} = 15 \ \text{A}, \ V_{R} = 600 \ \text{V} \\ V_{GE} = 0 \ \text{V}, \ T_{j} = 125 \ ^{\circ}\text{C} \\ \end{array} $		1,6 (1,6) 1 (0,8) 40 (53) 21 3,5 1,4	1,8 1,1 47 2,1	V V mΩ K/W A μC mJ	
	di <sub>F/dt</sub> = 570 A/µs					
Diode rec						
V <sub>F</sub> V <sub>(TO)</sub> r <sub>T</sub> R <sub>th(j-s)</sub>	$ I_F = A, T_j = 25 \degree C$ $T_j = \degree C$ per diode				V V mΩ K/W	
	tur sensor				-	
R <sub>ts</sub>	5 %, T <sub>r</sub> = 25 (100 ) °C		5000(493)		Ω	
Mechanic						
w M <sub>s</sub>	Mounting torque		30	2,5	g Nm	

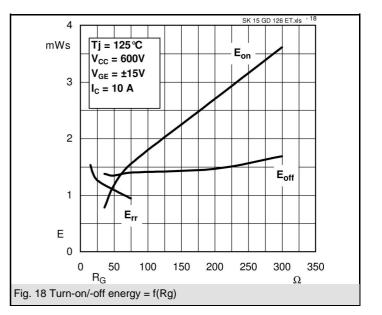


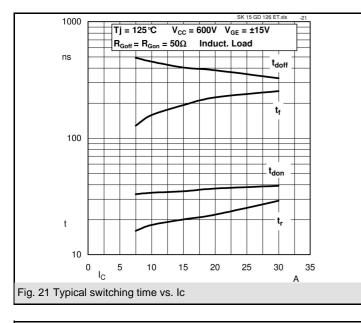
GD - ET

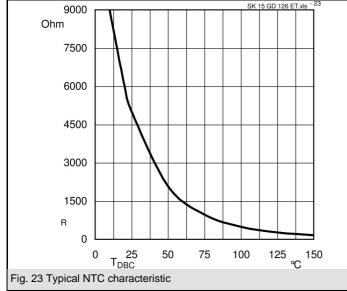


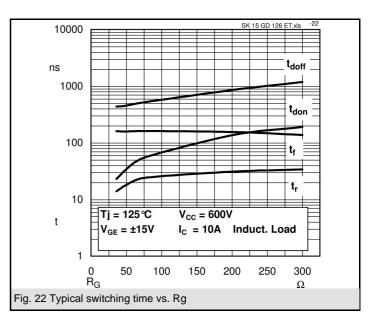


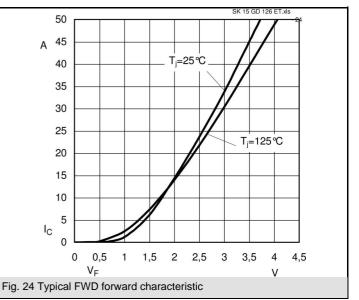






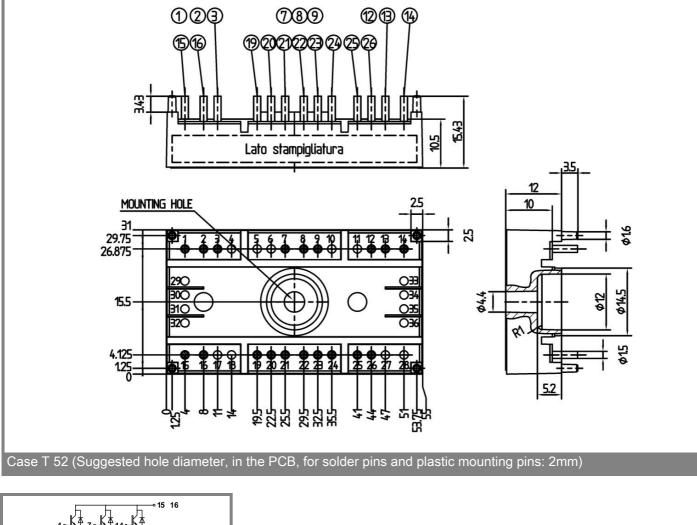


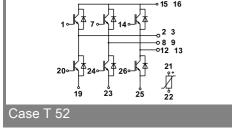




UL Recognized File no. E63 532







This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.